Material Specification

PROJECT			
Design name	: TEA1999TK Add-on Board		
Board-ID	: TEA1999DB1504	PCB number	: 0000-000-4091-R1-00
Reference	: Patrick van den Hurk	Date	: 14-02-2017
Size single board	: 18.00 x 25.00 mm.	Size panel board	: 110.00 x 145.00 mm.
Size tolerance	: +0.10 -0.20 mm.	Composition	: 5x5, See Panel Drawing
Total layer(s)	: **2**	Board thickness (+/- 10%.)	: **1.60 mm.**
Basic material	: **FR4**	Board finish	: ENIG
Cu thickness outer layer, finished	: **70 µm.**	Cu thickness inner layer	: **-- µm.**
SMD technologie	: **Yes, top side only**	Powerplanes	: No
Used via type(s)	: Through		
Pasta mask	: **Yes, top side only**	Peel-off mask	: No
Silkscreen	: **Yes, top side only**	Silkscreen colour	: White
Solder resist	: **Yes, top side only**	Solder resist colour	: Green

PLOTTER INFORMATION	
Units	: Milimeters
Gerber type	: RS274X
Data type	: Absolute X/Y-positive
Output code	: ASCII
Resolution	: 1/10000 mm.

NC DRILL PARAMETERS	
Units	: Imperial
Machine	: Excellon
Data format	: 3.5
Output code	: ASCII
Resolution	: 1/10000 inch

NON PLATED THROUGH HOLES	
Hole size tolerance, ≤ 0.2 mm.	: +0.05 -0.05 mm.
≥ 0.3 mm.	: +0.1 -0.1mm.
Position tolerance	: +0.1 -0.1mm.

PLATED THROUGH HOLES	
Hole size tolerance, ≤ 0.2 mm.	: +0.05 -0.05 mm.
≥ 0.3 mm.	: +0.1 -0.1mm.
Position tolerance	: +0.1 -0.1mm.

MILL BOARD OUTLINES

The position from the boardoutline and boardcutouts represent the exact centerline to complete the dimensions. The milltool has to be positioned near the centerline with a offset half the diameter from the tool.

SCORE BOARD OUTLINES

The position from the boardoutline represent the exact centerline to complete the dimensions. The score tool has to be positioned at the centerline.

BOARD PROPERTIES			
Min. isolation outer layer	: **200** µm.	Min. isolation inner layer	: **---** µm.
Min. track width outer layer	: **300** µm.	Min. track width inner layer	: **---** µm.
Min. hole diameter	: **1.0** mm.		

REMARKS

Manufacturer code allowed.
NXP Logo has to be **filled**.
~~Milling Through copper allowed.~~
Single board has to be panalized, the number of times see panel drawing.
Panel has breakaway edges (10.00mm).
Panel has scoring grooves, both directions.
Add text: 9999-000-40911 and has to be done only in the breakaway edge.
Create a top paste file from the panel. Send this back to customer.

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FILES INCLUDED		
Top Paste Mask	:	0000-000-4091-R1-00_SPT.gbx
Top Silkscreen	:	0000-000-4091-R1-00_SST.gbx
Top Solder Resist	:	0000-000-4091-R1-00_SMT.gbx
Top Signal Layer (L1)	:	0000-000-4091-R1-00_TOP.gbx
Bottom Signal Layer (L2)	:	0000-000-4091-R1-00_BOT.gbx
~~Bottom Solder Resist~~	:	~~0000-000-4091-R1-00_SMB.gbx~~
~~Bottom Silkscreen~~	:	~~0000-000-4091-R1-00_SSB.gbx~~
~~Bottom Paste Mask~~	:	~~0000-000-4091-R1-00_SPB.gbx~~
~~Milling Non Plated~~	:	~~0000-000-4091-R1-00_MNP.gbx~~
~~Milling Plated~~	:	~~0000-000-4091-R1-00_MPL.gbx~~
NC Drill	:	0000-000-4091-R1-00-1-2.drl
~~NC Route (slotted holes)~~	:	~~0000-000-4091-R1-00.rou~~
Mechanical Dimensions	:	0000-000-4091-R1-00_DRD.gbx/.pdf
Panel Drawing	:	0000-000-4091-R1-00_PNL.gbx/.pdf
This File	:	0000-000-4091-R1-00_MSP.pdf